BOARD CHARACTERISTICS

Copper Layer Count: 2 Board Thickness: 1.6000 mm

Board overall dimensions: 76.2000 mm x 73.8320 mm

Min track/spacing: 0.1524 mm / 0.1524 mm Min hole diameter: 0.2032 mm

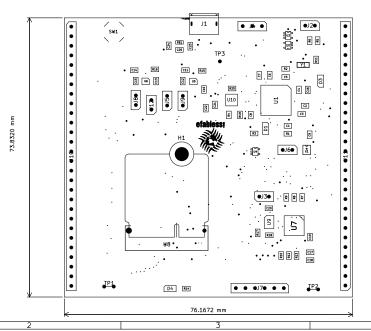
Copper Finish: None Impedance Control: No Castellated pads: No Plated Board Edge: No

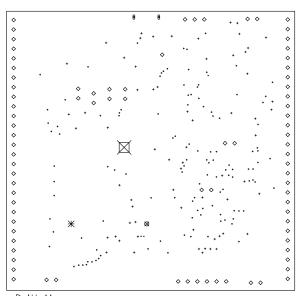
Edge card connectors: No

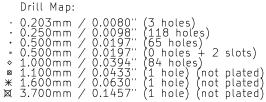
Layer Name	Туре	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Black	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	core	FR4	1.51 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Black	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	White	1	0

Notes:

- 1. Hole locations are indicated in seperate .drl file, included with the gerber package. That file takes precedence over this drawing.
- 2. Board outline is indicated in seperate Edge.Cuts file, included with the gerber package. That file takes precedence over this drawing.







Efabless

Sheet:

 $File: \ Fab-Drawing-clear-dev-v1.kicad_pcb$

Title: Clear Chip Development Board

 Size: A4
 Date:
 Rev: REV 1B

 KiCad E.D.A. pcbnew 7.0.10-7.0.10~ubuntu22.04.1
 Id: 1/1